

# MECHANICAL CASE OUTLINE

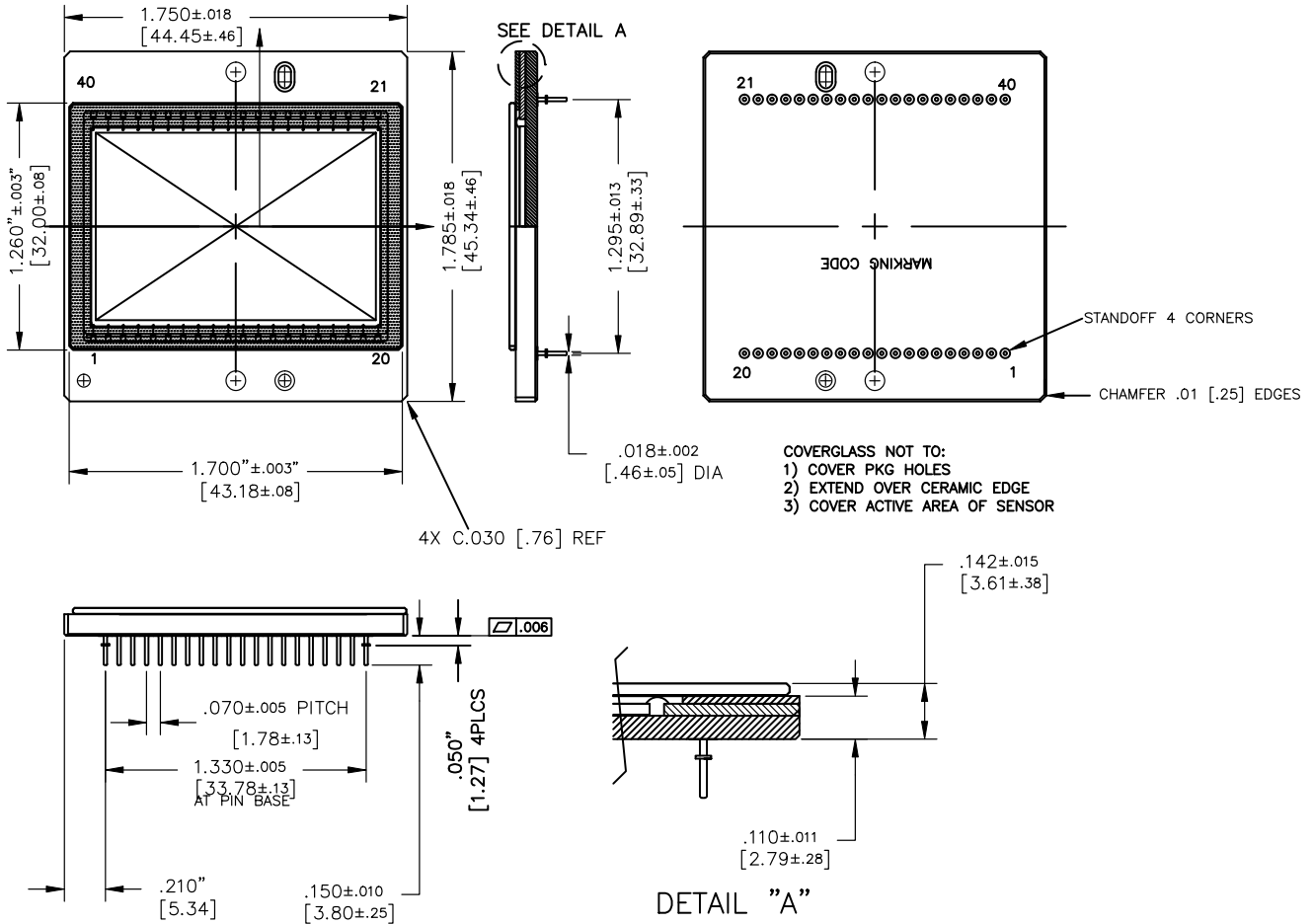
## PACKAGE DIMENSIONS

ON Semiconductor®



CPGA40, 44.45x45.34  
CASE 107EB  
ISSUE O

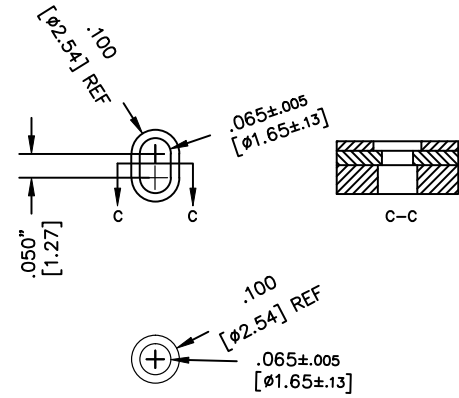
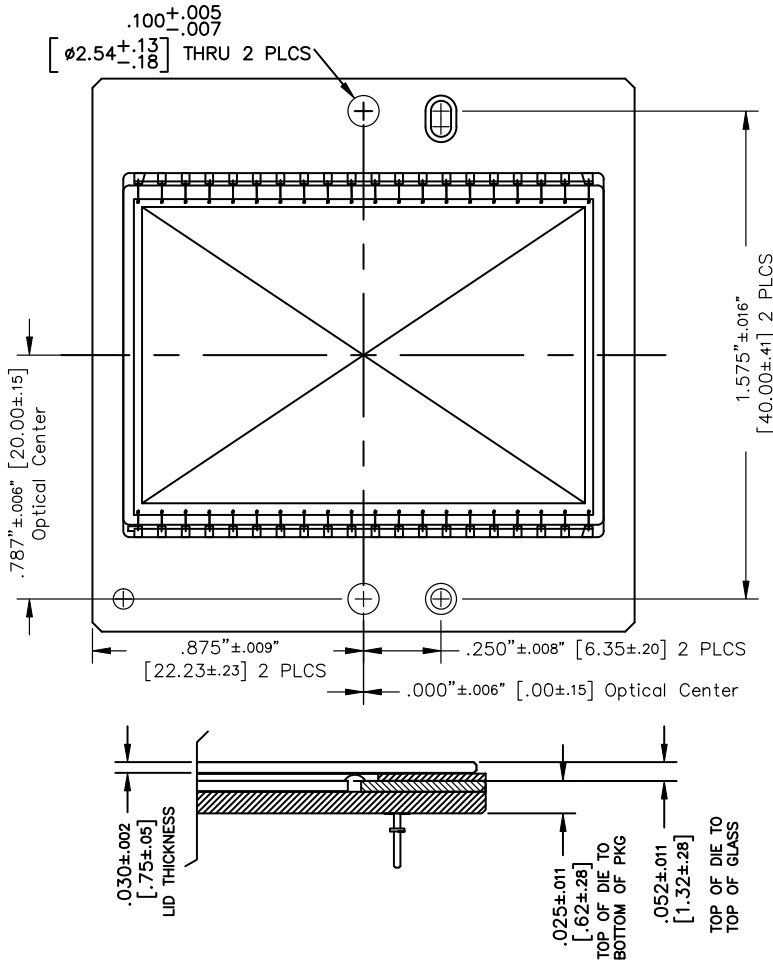
DATE 30 JUL 2014



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**CPGA40, 44.45x45.34**  
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- NOTES:  
 1. OPTICAL CENTER = PACKAGE CENTER  
 2. OPTICAL CENTER IS OFFSET FROM CENTER OF DIE BY X=0.000, Y=0.150 MM.  
 3. THE CENTER OF THE DIE IS y=-0.150 MM FROM THE CENTER OF THE PACKAGE.

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